

Title (en)

WAFER PROCESSING SYSTEM INCLUDING A ROBOT

Title (de)

WAFERBEARBEITUNGSSYSTEM MIT EINEM ROBOTER

Title (fr)

SYSTEME DE TRAITEMENT DE PLAQUETTES COMPRENANT UN ROBOT

Publication

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Application

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Priority

US 0032655 W 20001201

Abstract (en)

[origin: WO03012830A1] A wafer processing system occupies minimal floor space by using vertically mounted modules such as reactors, load locks, and cooling stations. Further saving in floor space is achieved by using a loading station which employs rotational motion to move a wafer carrier into a load lock. The wafer processing system includes a robot having extension, rotational, and vertical motion for accessing vertically mounted modules. The robot is internally cooled and has a heat resistant end-effector, making the robot compatible with high temperature semiconductor processing.

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IPC 8 full level

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